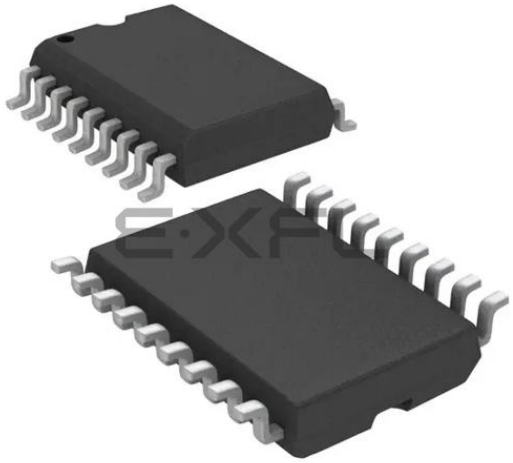

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Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16c712-20-so

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NOTES:

TABLE 1-1: PIC16C712/716 PINOUT DESCRIPTION (CONTINUED)

Pin Name	PIC16C712/716 DIP, SOIC	PIC16C712/716 SSOP	Pin Type	Buffer Type	Description
					PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT	6	7			
RB0			I/O	TTL	Digital I/O
INT			I	ST	External Interrupt
RB1/T1OSO/T1CKI	7	8			
RB1			I/O	TTL	Digital I/O
T1OSO			O	—	Timer1 oscillator output. Connects to crystal in oscillator mode.
T1CKI			I	ST	Timer1 external clock input.
RB2/T1OSI	8	9			
RB2			I/O	TTL	Digital I/O
T1OSI			I	—	Timer1 oscillator input. Connects to crystal in oscillator mode.
RB3/CCP1	9	10			
RB3			I/O	TTL	Digital I/O
CCP1			I/O	ST	Capture1 input, Compare1 output, PWM1 output.
RB4	10	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB5	11	12	I/O	TTL	Digital I/O Interrupt on change pin.
RB6	12	13	I/O	TTL	Digital I/O Interrupt on change pin.
			I	ST	ICSP programming clock.
RB7	13	14	I/O	TTL	Digital I/O Interrupt on change pin.
			I/O	ST	ICSP programming data.
VSS	5	5, 6	P	—	Ground reference for logic and I/O pins.
VDD	14	15, 16	P	—	Positive supply for logic and I/O pins.

Legend: TTL = TTL-compatible input CMOS = CMOS compatible input or output
ST = Schmitt Trigger input with CMOS levels
OD = Open drain output
SM = SMBus compatible input. An external resistor is required if this pin is used as an output
NPU = N-channel pull-up PU = Weak internal pull-up
No-P diode = No P-diode to VDD AN = Analog input or output
I = input O = output
P = Power L = LCD Driver

2.2.2.5 PIR1 Register

This register contains the individual flag bits for the peripheral interrupts.

Note:	Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-8: PIR1 REGISTER (ADDRESS 0Ch)

U-0	R/W-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF
bit7							bit0

R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7: **Unimplemented**: Read as '0'

bit 6: **ADIF**: A/D Converter Interrupt Flag bit
1 = An A/D conversion completed (must be cleared in software)
0 = The A/D conversion is not complete

bit 5-3: **Unimplemented**: Read as '0'

bit 2: **CCP1IF**: CCP1 Interrupt Flag bit
Capture Mode:
1 = A TMR1 register capture occurred (must be cleared in software)
0 = No TMR1 register capture occurred
Compare Mode:
1 = A TMR1 register compare match occurred (must be cleared in software)
0 = No TMR1 register compare match occurred
PWM Mode:
Unused in this mode

bit 1: **TMR2IF**: TMR2 to PR2 Match Interrupt Flag bit
1 = TMR2 to PR2 match occurred (must be cleared in software)
0 = No TMR2 to PR2 match occurred

bit 0: **TMR1IF**: TMR1 Overflow Interrupt Flag bit
1 = TMR1 register overflowed (must be cleared in software)
0 = TMR1 register did not overflow

2.2.2.6 PCON Register

The Power Control (PCON) register contains a flag bit to allow differentiation between a Power-on Reset (POR) to an external MCLR Reset or WDT Reset. These devices contain an additional bit to differentiate a Brown-out Reset condition from a Power-on Reset condition.

Note:	If the BODEN Configuration bit is set, $\overline{BOR}$ is '1' on Power-on Reset. If the BODEN Configuration bit is clear, $\overline{BOR}$ is unknown on Power-on Reset. The $\overline{BOR}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). $\overline{BOR}$ must then be set by the user and checked on subsequent resets to see if it is clear, indicating a brown-out has occurred.

FIGURE 2-9: PCON REGISTER (ADDRESS 8Eh)

U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-q
—	—	—	—	—	—	$\overline{POR}$	$\overline{BOR}$
bit7							bit0

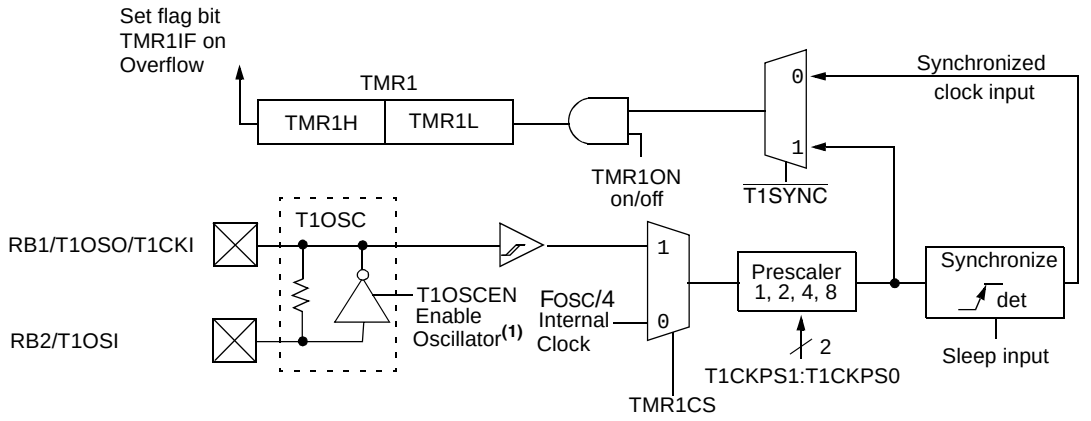
R = Readable bit
W = Writable bit
U = Unimplemented bit, read as '0'
-n = Value at POR Reset

bit 7-2: **Unimplemented:** Read as '0'

bit 1: **$\overline{POR}$**: Power-on Reset Status bit
1 = No Power-on Reset occurred
0 = A Power-on Reset occurred (must be set in software after a Power-on Reset occurs)

bit 0: **$\overline{BOR}$**: Brown-out Reset Status bit
1 = No Brown-out Reset occurred
0 = A Brown-out Reset occurred (must be set in software after a Brown-out Reset occurs)

FIGURE 5-2: TIMER1 BLOCK DIAGRAM



Note 1: When the T1OSCEN bit is cleared, the inverter and feedback resistor are turned off. This eliminates power drain.

5.2 Timer1 Module and PORTB Operation

When Timer1 is configured as timer running from the main oscillator, PORTB<2:1> operate as normal I/O lines. When Timer1 is configured to function as a counter however, the clock source selection may affect the operation of PORTB<2:1>. Multiplexing details of the Timer1 clock selection on PORTB are shown in Figure 3-4 and Figure 3-5.

The clock source for Timer1 in the Counter mode can be from one of the following:

1. External circuit connected to the RB1/T1OSO/T1CKI pin
2. Firmware controlled DATACCP<0> bit, DT1CKI
3. Timer1 oscillator

Table 5-1 shows the details of Timer1 mode selections, control bit settings, TMR1 and PORTB operations.

TABLE 5-1: TMR1 MODULE AND PORTB OPERATION

TMR1 Module Mode	Clock Source	Control Bits	TMR1 Module Operation	PORTB<2:1> Operation
Off	N/A	T1CON = --xx 0x00	Off	PORTB<2:1> function as normal I/O
Timer	Fosc/4	T1CON = --xx 0x01	TMR1 module uses the main oscillator as clock source. TMR1ON can turn on or turn off Timer1.	PORTB<2:1> function as normal I/O
Counter	External circuit	T1CON = --xx 0x11 TR1SCCP = ---- -x-1	TMR1 module uses the external signal on the RB1/T1OSO/T1CKI pin as a clock source. TMR1ON can turn on or turn off Timer1. DT1CK can read the signal on the RB1/T1OSO/T1CKI pin.	PORTB<2> functions as normal I/O. PORTB<1> always reads '0' when configured as input. If PORTB<1> is configured as output, reading PORTB<1> will read the data latch. Writing to PORTB<1> will always store the result in the data latch, but not to the RB1/T1OSO/T1CKI pin. If the TMR1CS bit is cleared (TMR1 reverts to the timer mode), then pin PORTB<1> will be driven with the value in the data latch.
	Firmware	T1CON = --xx 0x11 TR1SCCP = ---- -x-0	DATACCP<0> bit drives RB1/T1OSO/T1CKI and produces the TMR1 clock source. TMR1ON can turn on or turn off Timer1. The DATACCP<0> bit, DT1CK, can read and write to the RB1/T1OSO/T1CKI pin.	
	Timer1 oscillator	T1CON = --xx 1x11	RB1/T1OSO/T1CKI and RB2/T1OSI are configured as a 2 pin crystal oscillator. RB1/T1OSI/T1CKI is the clock input for TMR1. TMR1ON can turn on or turn off Timer1. DATACCP<1> bit, DT1CK, always reads '0' as input and can not write to the RB1/T1OSO/T1CK1 pin.	PORTB<2:1> always read '0' when configured as inputs. If PORTB<2:1> are configured as outputs, reading PORTB<2:1> will read the data latches. Writing to PORTB<2:1> will always store the result in the data latches, but not to the RB2/T1OSI and RB1/T1OSO/T1CKI pins. If the TMR1CS and T1OSCEN bits are cleared (TMR1 reverts to the timer mode and TMR1 oscillator is disabled), then pin PORTB<2:1> will be driven with the value in the data latches.

8.4 A/D Conversions

Note:	The GO/$\overline{\text{DONE}}$ bit should **NOT** be set in the same instruction that turns on the A/D.

8.5 Use of the CCP Trigger

An A/D conversion can be started by the "Special Event Trigger" of the CCP1 module. This requires that the CCP1M3:CCP1M0 bits (CCP1CON<3:0>) be programmed as 1011 and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/$\overline{\text{DONE}}$ bit will be set, starting the A/D conversion, and the Timer1 counter will be reset to zero. Timer1 is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving the ADRES to the desired location). The appropriate analog input channel must be selected and the minimum acquisition done before the "Special Event Trigger" sets the GO/$\overline{\text{DONE}}$ bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), then the "Special Event Trigger" will be ignored by the A/D module, but will still reset the Timer1 counter.

TABLE 8-2: SUMMARY OF A/D REGISTERS

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
05h	PORTA	—	—	—(1)	RA4	RA3	RA2	RA1	RA0	--xx xxxx	--xu uuuu
0Bh,8Bh	INTCON	GIE	PEIE	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	—	—	—	CCP1IF	TMR2IF	TMR1IF	-0-- -000	-0-- -000
1Eh	ADRES	A/D Result Register								xxxx xxxx	uuuu uuuu
1Fh	ADCON0	ADCS1	ADCS0	CHS2	CHS1	CHS0	GO/$\overline{\text{DONE}}$	—	ADON	0000 00-0	0000 00-0
85h	TRISA	—	—	—(1)	PORTA Data Direction Register					---1 1111	---1 1111
8Ch	PIE1	—	ADIE	—	—	—	CCP1IE	TMR2IE	TMR1IE	-0-- -000	-0-- 0000
9Fh	ADCON1	—	—	—	—	—	PCFG2	PCFG1	PCFG0	---- -000	---- -000

Legend: x = unknown, u = unchanged, — = unimplemented read as '0'. Shaded cells are not used for A/D conversion.
Note 1: Reserved bits; Do Not Use.

FIGURE 9-1: CONFIGURATION WORD

$\overline{CP1}$	$\overline{CP0}$	$\overline{CP1}$	$\overline{CP0}$	$\overline{CP1}$	$\overline{CP0}$	—	BODEN	$\overline{CP1}$	$\overline{CP0}$	$\overline{PWRTE}$	WDTE	FOSC1	FOSC0
bit13													bit0

Register:CONFIG
Address2007h

bit 13-8, 5-4: **$\overline{CP1}$:$\overline{CP0}$**: Code Protection bits **(2)**
Code Protection for 2K Program memory (PIC16C716)
11 = Programming code protection off
10 = 0400h-07FFh code protected
01 = 0200h-03FFh code protected
00 = 0000h-07FFh code protected

bit 13-8, 5-4:
Code Protection for 1K Program memory bits (PIC16C712)
11 = Programming code protection off
10 = Programming code protection off
01 = 0200h-03FFh code-protected
00 = 0000h-03FFh code-protected

bit 7: **Unimplemented**: Read as '1'

bit 6: **BODEN**: Brown-out Reset Enable bit **(1)**
1 = BOR enabled
0 = BOR disabled

bit 3: **$\overline{PWRTE}$**: Power-up Timer Enable bit **(1)**
1 = PWRT disabled
0 = PWRT enabled

bit 2: **WDTE**: Watchdog Timer Enable bit
1 = WDT enabled
0 = WDT disabled

bit 1-0: **FOSC1:FOSC0**: Oscillator Selection bits
11 = RC oscillator
10 = HS oscillator
01 = XT oscillator
00 = LP oscillator

Note 1: Enabling Brown-out Reset automatically enables Power-up Timer (PWRT) regardless of the value of bit $\overline{PWRTE}$. Ensure the Power-up Timer is enabled anytime Brown-out Reset is enabled.

2: All of the $\overline{CP1}$:$\overline{CP0}$ pairs have to be given the same value to enable the code protection scheme listed.

9.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON has two bits.

Bit 0 is Brown-out Reset Status bit, $\overline{BOR}$. If the BODEN Configuration bit is set, $\overline{BOR}$ is '1' on Power-on Reset. If the BODEN Configuration bit is clear, $\overline{BOR}$ is unknown on Power-on Reset.

The $\overline{BOR}$ Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). $\overline{BOR}$ must then be set by the user and checked on subsequent Resets to see if it is clear, indicating a brown-out has occurred.

Bit 1 is $\overline{POR}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 9-3: TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power-up		Brown-out	Wake-up from Sleep
	$\overline{PWRTE}$ = 0	$\overline{PWRTE}$ = 1		
XT, HS, LP	72 ms + 1024TOSC	1024TOSC	72 ms + 1024TOSC	1024TOSC
RC	72 ms	—	72 ms	—

TABLE 9-4: STATUS BITS AND THEIR SIGNIFICANCE

$\overline{POR}$	$\overline{BOR}$	$\overline{TO}$	$\overline{PD}$	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, $\overline{TO}$ is set on $\overline{POR}$
0	x	x	0	Illegal, $\overline{PD}$ is set on $\overline{POR}$
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	$\overline{MCLR}$ Reset during normal operation
1	1	1	0	$\overline{MCLR}$ Reset during Sleep or interrupt wake-up from Sleep

TABLE 9-5: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	---- --0x
$\overline{MCLR}$ Reset during normal operation	000h	000u uuuu	---- --uu
$\overline{MCLR}$ Reset during Sleep	000h	0001 0uuu	---- --uu
WDT Reset	000h	0000 1uuu	---- --uu
WDT Wake-up	PC + 1	uuu0 0uuu	---- --uu
Brown-out Reset	000h	0001 1uuu	---- --u0
Interrupt wake-up from Sleep	PC + 1(1)	uuu1 0uuu	---- --uu

Legend: u = unchanged, x = unknown, – = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

9.13.2 WAKE-UP USING INTERRUPTS

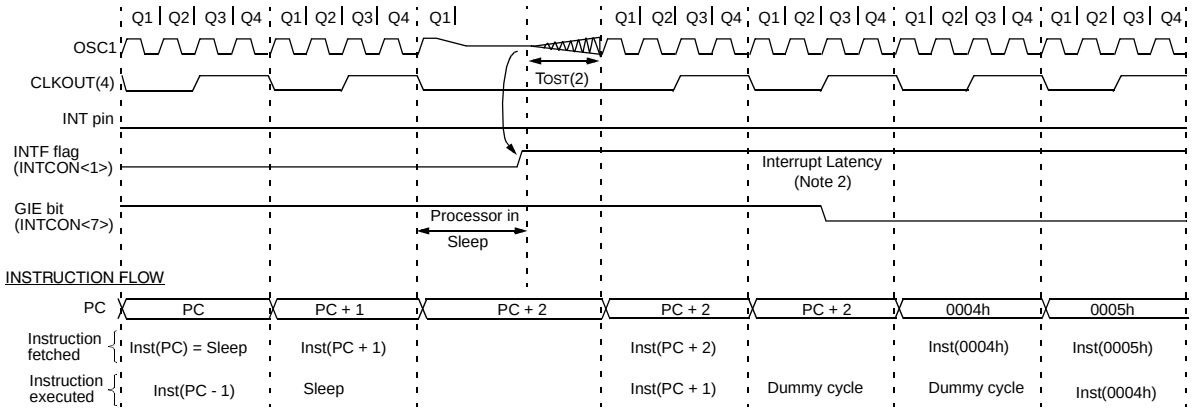
When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

- If the interrupt occurs **before** the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the $\overline{TO}$ bit will not be set and $\overline{PD}$ bits will not be cleared.
- If the interrupt occurs **during or after** the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the $\overline{TO}$ bit will be set and the $\overline{PD}$ bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the $\overline{PD}$ bit. If the $\overline{PD}$ bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a SLEEP instruction.

FIGURE 9-17: WAKE-UP FROM SLEEP THROUGH INTERRUPT



Note 1: XT, HS or LP Oscillator mode assumed.
2: TOST = 1024TOSC (drawing not to scale) This delay will not be there for RC Osc mode.
3: GIE = 1 assumed. In this case after wake-up, the processor jumps to the interrupt routine. If GIE = 0, execution will continue in-line.
4: CLKOUT is not available in these osc modes, but shown here for timing reference.

9.14 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	Microchip does not recommend code protecting windowed devices.

9.15 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. It is recommended that only the 4 Least Significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming™ (ICSP™) Guide, (DS30277).

12.0 ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (†)

Ambient temperature under bias ..... -55°C to +125°C
Storage temperature ..... -65°C to +150°C
Voltage on any pin with respect to V_{SS} (except V_{DD}, $\overline{MCLR}$, and RA4) ..... -0.3V to (V_{DD} + 0.3V)
Voltage on V_{DD} with respect to V_{SS} ..... -0.3V to +7.5V
Voltage on $\overline{MCLR}$ with respect to V_{SS} **(Note 2)** ..... 0V to +13.25V
Voltage on RA4 with respect to Vss ..... 0V to +8.5V
Total power dissipation **(Note 1)** (PDIP and SOIC) 1.0W
Total power dissipation **(Note 1)** (SSOP) 0.65W
Maximum current out of V_{SS} pin ..... 300 mA
Maximum current into V_{DD} pin ..... 250 mA
Input clamp current, I_{IK} (V_I < 0 or V_I > V_{DD}) ..... ±20 mA
Output clamp current, I_{OK} (V_O < 0 or V_O > V_{DD}) ..... ±20 mA
Maximum output current sunk by any I/O pin ..... 25 mA
Maximum output current sourced by any I/O pin ..... 25 mA
Maximum current sunk by PORTA and PORTB (combined) ..... 200 mA
Maximum current sourced by PORTA and PORTB (combined) ..... 200 mA

Note 1: Power dissipation is calculated as follows: $P_{dis} = V_{DD} \times \{I_{DD} - \sum I_{OH}\} + \sum \{(V_{DD}-V_{OH}) \times I_{OH}\} + \sum(V_{OL} \times I_{OL})$

2: Voltage spikes below V_{SS} at the $\overline{MCLR}/V_{PP}$ pin, inducing currents greater than 80 mA, may cause latch-up. Thus, a series resistor of 50-100Ω should be used when applying a "low" level to the $\overline{MCLR}/V_{PP}$ pin rather than pulling this pin directly to V_{SS}.

† NOTICE: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions above those indicated in the operation listings of this specification is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

12.2 DC Characteristics: PIC16LC712/716-04 (Commercial, Industrial)

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for commercial -40°C ≤ TA ≤ +85°C for industrial				
Param No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
D001	VDD	**Supply Voltage**	2.5 VBOR*	— —	5.5 5.5	V V	 BOR enabled **(Note 7)**
D002*	VDR	**RAM Data Retention Voltage(1)**	—	1.5	—	V	
D003	VPOR	**VDD Start Voltage** to ensure internal Power-on Reset signal	—	VSS	—	V	See section on Power-on Reset for details
D004* D004A*	SVDD	**VDD Rise Rate** to ensure internal Power-on Reset signal	0.05 TBD	— —	— —	V/ms	PWRT enabled ($\overline{\text{PWRTE}}$ bit clear) PWRT disabled ($\overline{\text{PWRTE}}$ bit set) See section on Power-on Reset for details
D005	VBOR	**Brown-out Reset** voltage trip point	3.65	—	4.35	V	BODEN bit set
D010 D010A	IDD	**Supply Current(2,5)**	— —	2.0 22.5	3.8 48	mA µA	XT, RC osc modes FOSC = 4 MHz, VDD = 3.0V **(Note 4)** LP osc mode FOSC = 32 kHz, VDD = 3.0V, WDT disabled
D020 D021 D021A	IPD	**Power-down Current(3,5)**	— — —	7.5 0.9 0.9	30 5 5	µA µA µA	VDD = 3.0V, WDT enabled, -40°C to +85°C VDD = 3.0V, WDT disabled, 0°C to +70°C VDD = 3.0V, WDT disabled, -40°C to +85°C
D022* D022A*	ΔIWDT ΔIBOR	**Module Differential Current(6)** Watchdog Timer Brown-out Reset	— —	6.0 TBD	20 200	µA µA	WDTE bit set, VDD = 4.0V BODEN bit set, VDD = 5.0V
1A	FOSC	LP Oscillator Operating Frequency RC Oscillator Operating Frequency XT Oscillator Operating Frequency HS Oscillator Operating Frequency	0 0 0 0	— — — —	200 4 4 20	KHz MHz MHz MHz	All temperatures All temperatures All temperatures All temperatures

* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: This is the limit to which VDD can be lowered without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern, and temperature also have an impact on the current consumption.
The test conditions for all IDD measurements in active operation mode are:
OSC1 = external square wave, from rail-to-rail; all I/O pins tri-stated, pulled to VDD,
$\overline{\text{MCLR}}$ = VDD; WDT enabled/disabled as specified.

3: The power-down current in Sleep mode does not depend on the oscillator type. Power-down current is measured with the part in Sleep mode, with all I/O pins in high-impedance state and tied to VDD and VSS.

4: For RC Osc mode, current through REXT is not included. The current through the resistor can be estimated by the formula Ir = VDD/2REXT (mA) with REXT in kOhm.

5: Timer1 oscillator (when enabled) adds approximately 20 µA to the specification. This value is from characterization and is for design guidance only. This is not tested.

6: The Δ current is the additional current consumed when this peripheral is enabled. This current should be added to the base IDD or IPD measurement.

7: This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device will operate correctly to this trip point.

12.4.3 TIMING DIAGRAMS AND SPECIFICATIONS

FIGURE 12-4: EXTERNAL CLOCK TIMING

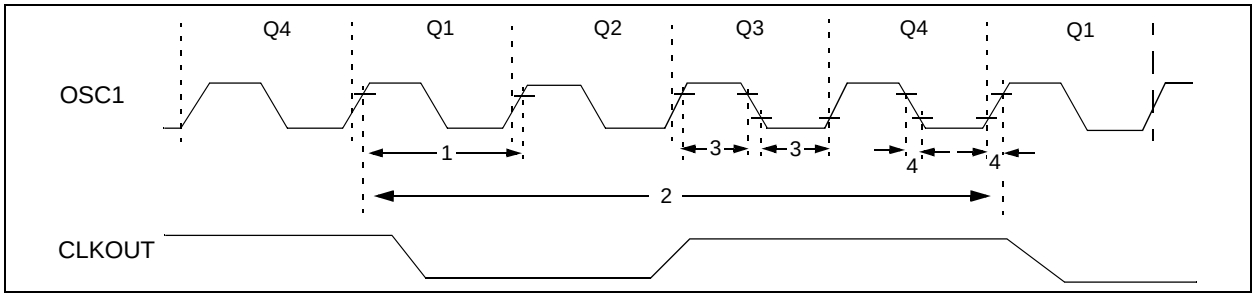


TABLE 12-2: EXTERNAL CLOCK TIMING REQUIREMENTS

Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
1A	FOSC	**External CLKIN Frequency (Note 1)**	DC	—	4	MHz	RC and XT osc modes
			DC	—	4	MHz	HS osc mode (-04)
			DC	—	20	MHz	HS osc mode (-20)
			DC	—	200	kHz	LP osc mode
		Oscillator Frequency (Note 1)	DC	—	4	MHz	RC osc mode
			0.1	—	4	MHz	XT osc mode
			4	—	20	MHz	HS osc mode
			5	—	200	kHz	LP osc mode
1	TOSC	**External CLKIN Period (Note 1)**	250	—	—	ns	RC and XT osc modes
			250	—	—	ns	HS osc mode (-04)
			50	—	—	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
		Oscillator Period (Note 1)	250	—	—	ns	RC osc mode
			250	—	10,000	ns	XT osc mode
			250	—	250	ns	HS osc mode (-04)
			50	—	250	ns	HS osc mode (-20)
			5	—	—	µs	LP osc mode
2	TCY	**Instruction Cycle Time (Note 1)**	200	—	DC	ns	TCY = 4/FOSC
3*	TosL, TosH	**External Clock in (OSC1) High or Low Time**	100	—	—	ns	XT oscillator
			2.5	—	—	µs	LP oscillator
			15	—	—	ns	HS oscillator
4*	TosR, TosF	**External Clock in (OSC1) Rise or Fall Time**	—	—	25	ns	XT oscillator
			—	—	50	ns	LP oscillator
			—	—	15	ns	HS oscillator

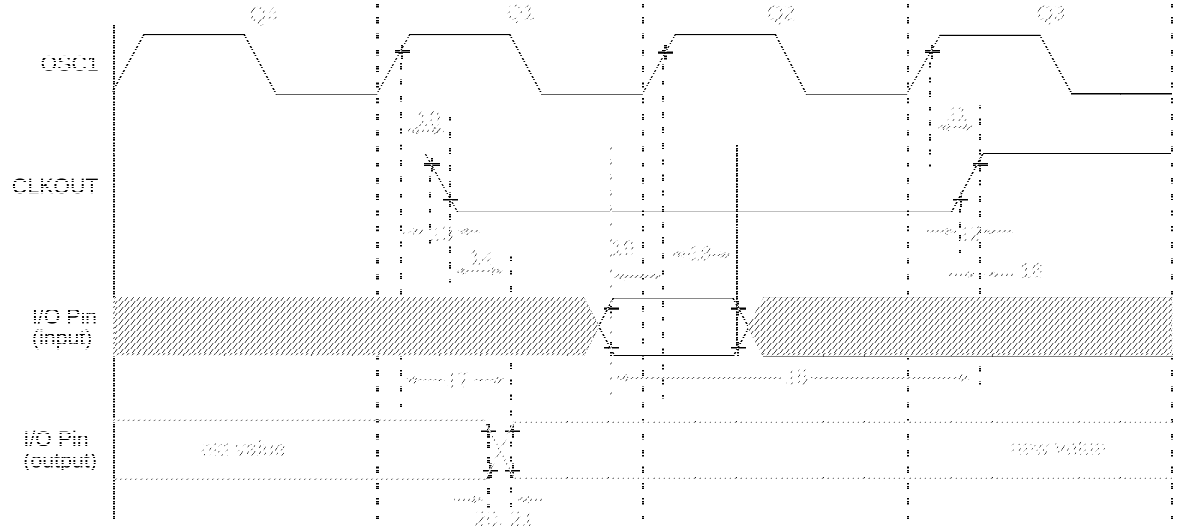
* These parameters are characterized but not tested.

† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min." values with an external clock applied to the OSC1/CLKIN pin.

When an external clock input is used, the "Max." cycle time limit is "DC" (no clock) for all devices.

FIGURE 12-5: CLKOUT AND I/O TIMING



Note: Refer to Figure 12-3 for load conditions.

TABLE 12-3: CLKOUT AND I/O TIMING REQUIREMENTS

Param No.	Sym.	Characteristic		Min.	Typ†	Max.	Units	Conditions
10*	TosH2ckL	OSC1↑ to CLKOUT↓		—	75	200	ns	**Note 1**
11*	TosH2ckH	OSC1↑ to CLKOUT↑		—	75	200	ns	**Note 1**
12*	TckR	CLKOUT rise time		—	35	100	ns	**Note 1**
13*	TckF	CLKOUT fall time		—	35	100	ns	**Note 1**
14*	TckL2ioV	CLKOUT Ø to Port out valid		—	—	0.5TCY + 20	ns	**Note 1**
15*	TioV2ckH	Port in valid before CLKOUT ↑		Tosc + 200	—	—	ns	**Note 1**
16*	TckH2ioI	Port in hold after CLKOUT ↑		0	—	—	ns	**Note 1**
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid		—	50	150	ns	
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	Standard	100	—	—	ns	
18A*			Extended (LC)	200	—	—	ns	
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)		0	—	—	ns	
20*	TioR	Port output rise time	Standard	—	10	40	ns	
20A*			Extended (LC)	—	—	80	ns	
21*	TioF	Port output fall time	Standard	—	10	40	ns	
21A*			Extended (LC)	—	—	80	ns	
22††*	TINP	INT pin high or low time		TCY	—	—	ns	
23††*	TRBP	RB7:RB4 change INT high or low time		TCY	—	—	ns	

* These parameters are characterized but not tested.

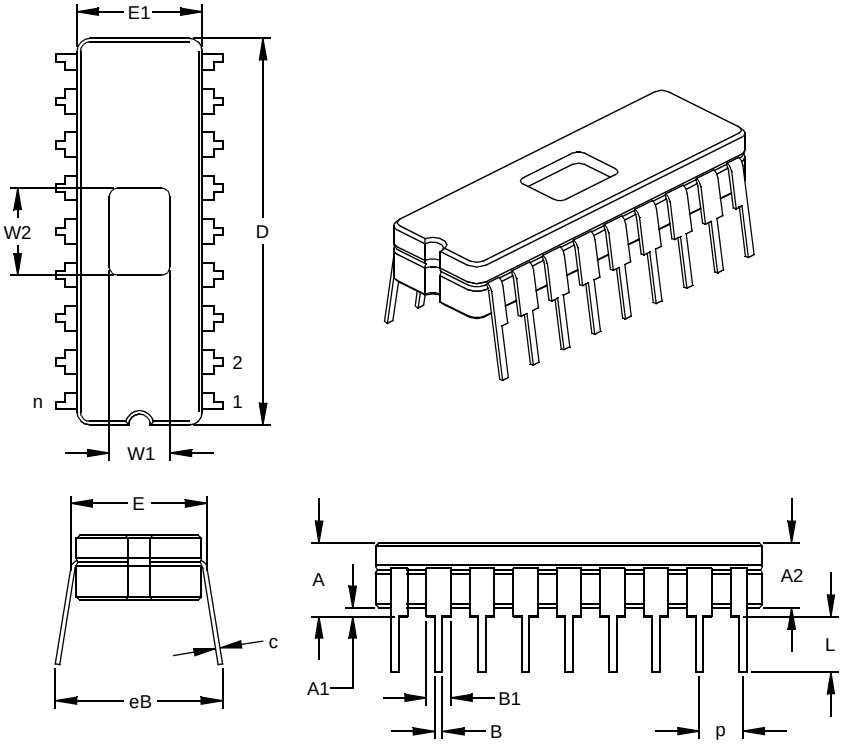
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

†† These parameters are asynchronous events not related to any internal clock edge.

Note1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

18-Lead Ceramic Dual In-line with Window (JW) – 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		18			18	
Pitch	p		.100			2.54	
Top to Seating Plane	A	.170	.183	.195	4.32	4.64	4.95
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19
Standoff	A1	.015	.023	.030	0.38	0.57	0.76
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49
Overall Length	D	.880	.900	.920	22.35	22.86	23.37
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81
Lead Thickness	c	.008	.010	.012	0.20	0.25	0.30
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52
Lower Lead Width	B	.016	.019	.021	0.41	0.47	0.53
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80
Window Width	W1	.130	.140	.150	3.30	3.56	3.81
Window Length	W2	.190	.200	.210	4.83	5.08	5.33

* Controlling Parameter
§ Significant Characteristic
JEDEC Equivalent: MO-036
Drawing No. C04-010

NOTES:

NOTES:

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